



Material Content Data Sheet



Sales Product Name		BSS139 H6327		Issued		2. August 2018		
MA#		MA001231782						
Package		PG-SOT23-3-5		Weight*		9.36 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.004	0.05		471	
	noble metal	gold	7440-57-5	0.017	0.18		1828	
	inorganic material	silicon	7440-21-3	0.194	2.07	2.30	20720	23019
leadframe	non noble metal	chromium	7440-47-3	0.009	0.10		966	
	inorganic material	silicon	7440-21-3	0.001	0.01		64	
	non noble metal	titanium	7440-32-6	0.003	0.03		322	
	non noble metal	copper	7440-50-8	3.000	32.07	32.21	320688	322040
wire	non noble metal	copper	7440-50-8	0.007	0.08	0.08	784	784
encapsulation	organic material	carbon black	1333-86-4	0.057	0.61		6076	
	plastics	epoxy resin	-	1.222	13.06		130626	
	inorganic material	silicondioxide	60676-86-0	4.405	47.08	60.75	470862	607564
leadfinish	non noble metal	tin	7440-31-5	0.152	1.62	1.62	16194	16194
plating	noble metal	silver	7440-22-4	0.284	3.04	3.04	30399	30399
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com